

REMARKS

This application has been carefully reviewed in light of the Office Action mailed March 14, 2006 (the "Office Action"). Claims 1, 15, and 25 have been amended and Claims 6 and 20 have been canceled. Thus, Claims 1-5, 7-19, and 21-25 remain in the application of which Claims 1, 15, and 25 are the only independent claims. Favorable action on the merits of the claims is earnestly solicited.

Rejections Under 35 U.S.C. §102 and §103

The Office Action rejects Claims 1-5, 10-12, 15-19, 22 and 23 under 35 U.S.C. 102(e) as being anticipated by U.S. Patent No. 6,576,998 to Hoffman ("*Hoffman*") and rejects Claims 6 and 20 under 35 U.S.C. 103(a) as being unpatentable over *Hoffman*, in view of U.S. PG Publication No. 2002/0125558 to Akram et al ("*Akram*"). Applicant respectfully traverses these rejections for the reasons described below.

Claim 1 has been amended to incorporate the limitations of Claim 6 in addition to a further limitation such that Claim 1 currently recites "... said third circuit portion having third and fourth electrically conductive parts which are respectively coupled to said first and second electrically conductive parts by a thermosonic bond and a thermocompression bond such that said first and second electrically conductive parts rigidly support said first circuit component adjacent said third circuit component; ..." This recitation is not disclosed taught, or suggested by *Hoffman*, *Akram*, or any combination thereof. The Examiner concedes that the thermosonic and thermocompression bonds of *Akram* are not disclosed by *Hoffman* (See Office Action, page 5). From this assertion, the Examiner concludes that it would have been obvious to incorporate the thermosonic and thermocompression bonds of *Akram* into *Hoffman* in order to form the claimed structure. However, *Akram* only teaches ultrasonic bonding of the first and second electrically conducting parts to the third circuit with **bond wires** using known industry standard wirebonding techniques (See *Akram*, paragraph 7).

There exists no teaching within *Akram* that suggests the ability to utilize first and second electrically conducting parts that provide structural support for the first circuit component adjacent the third circuit component. The structure of these bond wires are inherently flexible and therefore insufficient to provide any structural support for the third

circuit portion adjacent the first circuit portion. To remedy the problem of bond wires that are incapable of providing structural support, *Akram* only teaches the use of an adhesively coated, insulated film layer deposited on the first circuit portion (See *Akram*, paragraph 9). *Akram* has not contemplated ultrasonically bonding at least a first and second electrically conducting parts to the third circuit portion for electrical communication as well as for providing structural support as claimed by Applicants.

Therefore, neither *Hoffman* or *Akram* disclose, teach, or suggest bonding the first and second electrically conducting parts to the third circuit portion using a thermosonic and thermocompression bond such that the first and second electrically conductive parts rigidly support said first circuit component adjacent said third circuit component as claimed by Applicant. For at least these reasons, Claim 1 is allowable, as are all claims depending therefrom. Claim 15, and 25 is allowable for analogous reasons, as are all claims depending therefrom. Reconsideration and favorable action is requested.

Conclusion

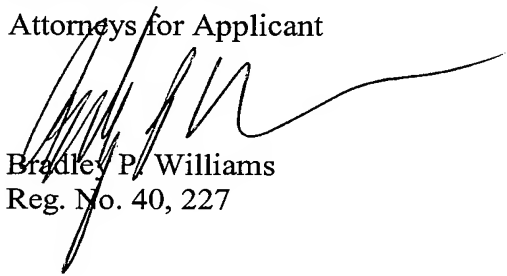
Applicant has made an earnest attempt to place this case in condition for allowance. For at least the foregoing reasons, Applicant respectfully requests full allowance of all pending claims.

If the Examiner believes that a telephone conference would advance prosecution of this Application in any manner, the Examiner is invited to contact the undersigned Attorney for Applicant at the Examiner's convenience.

Applicant believes that no fee is due. However, the Commissioner is hereby authorized to charge any additional fees or credit any overpayments to Deposit Account No. 02-0384 of Baker Botts L.L.P.

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